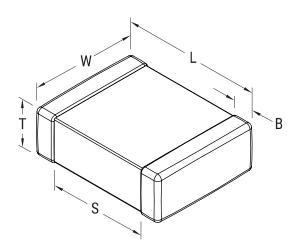


C1210C223JBGACTU

Aliases (C1210C223JBGAC7800) SMD Comm COG HV, Ceramic, 0.022 uF, 5%, 630 VDC, COG, SMD, MLCC, Ultra-Stable, Low Loss, Class I, 1210, 1.5 mm



Click here for the 3D model.

General Information	
Series	SMD Comm COG HV
Style	SMD Chip
Description	SMD, MLCC, Ultra-Stable, Low Loss, Class I
Features	Ultra-Stable, Low Loss, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	78 mg
Shelf Life	78 Weeks
MSL	1

		Specifications
	1210	Capacitance
	3.2mm +/-0.2mm	Measurement Condition
	2.5mm +/-0.2mm	Tolerance
	2mm +/-0.20mm	Voltage DC
	1.5mm MIN	Dielectric Withstanding Voltag
	0.5mm +/-0.25mm	Temperature Range
		Temp. Coefficient
ications	T&P 180mm Plastic Tape	Capacitance Change with Reference to +25°C and 0 VDC

Packaging Specification	s
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Dimensions Chip Size

L W T S B

PackagingT&R, 1Packaging Quantity2000

T&R, 180mm, Plastic Tape 2000

Specifications	
Capacitance	0.022 uF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	5%
Voltage DC	630 VDC
Dielectric Withstanding Voltage	819 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	45.4545 GOhms

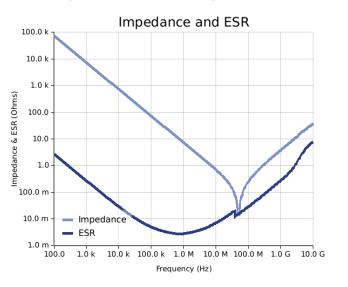
Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

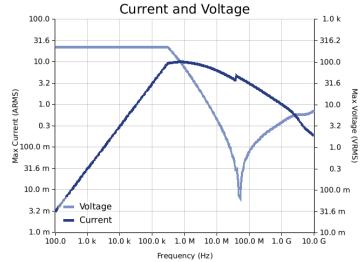


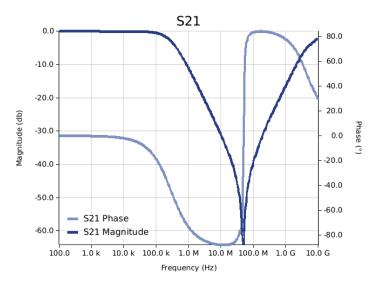
C1210C223JBGACTU Aliases (C1210C223JBGAC7800) SMD Comm C0G HV, Ceramic, 0.022 uF, 5%, 630 VDC, C0G, SMD, MLCC, Ultra-Stable, Low Loss, Class I, 1210, 1.5 mm

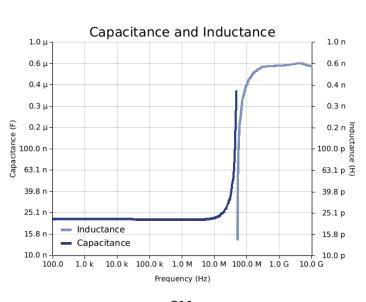
Simulations

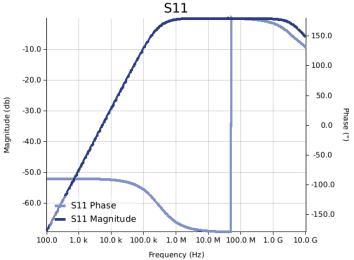
For the complete simulation environment please visit K-SIM.













C1210C223JBGACTU

Aliases (C1210C223JBGAC7800) SMD Comm COG HV, Ceramic, 0.022 uF, 5%, 630 VDC, COG, SMD, MLCC, Ultra-Stable, Low Loss, Class I, 1210, 1.5 mm

These are simulations.

This is not a specification!

The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

The responses shown do not represent a specified or implied maximum capability of the device for all applications.

- The ESR used for ripple "Ripple Current/Voltage vs. Frequency" plots is the ESR at ambient temperature.

- The ESR used for https:// temperature Rise vs. Ripple Current/ voltage vs. Frequency plots is the ESR at ambient temperature.
 The ESR in the "Temperature Rise vs. Ripple Current" plots is adjusted to each incremental temperature rise before the power and ripple current is calculated.
 The effects shown herein are based on measured data from a multiple part sample of the parts in question.
 Ripple capability of this device will be factored by thermal resistance (Rth) created by circuit traces (addi affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.
 The peak voltages generated in the "Temperature Rise vs. Combined Ripple Currents" plot are calculated for each frequency and are not combined with voltages
- generated at any other harmonics. Please consult with the catalog or field applications engineer for maximum capability of the device in specific applications.

All product information and data (collectively, the "Information") are subject to change without notice.

KEMET K-SIM is designed to simulate behavior of components with respect to frequency, ambient temperature, and DC bias levels. The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation effects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

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If you have any questions please contact K-SIM.